

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CID6 Series Connector System	SPEC.NO.: SPCI125A
REVISIONS			PAGE: 1/3

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

2.1 Industry standards :

EIA-364 electrical connector /socket test procedures including environmental classifications

3. APPLICABLE SERIES NO: CID6 Series (CID624P1H00-NH)

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 0.8 mm (.031") ~ 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED : Eisley APPROVED : Eisley VERIFIED : Sandy .

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CID6 Series Connector System	SPEC.NO.: SPCI125A
REVISIONS			PAGE: 2/3

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		2A 200V AC/DC (r.m.s.)
7.2	Contact resistance	Mated connector, Contact: measured by dry circuit of DC 20 mV max. , 10 mA(DC).	Less than 20 mΩ max.
7.3	Dielectric strength	When applied AC 500 V 1 minute between adjacent terminal or ground	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent contacts of a mating specimen to measure insulation resistance	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Insertion/ withdrawal force	Apply axial pull out force at the speed rate of 25± 3 mm/min.	I.F is 0.40Kgf max. per pin 24pin:9.6Kgf Max W.F is 0.02Kgf max. per pin 24pin:0.48~2.66Kgf
8.2	Terminal Retention force	Samples should be exposed 72h Min. at ambient atmosphere after molding. Apply axial pull out force at the speed rate of 25± 3 mm/min.	MB Side: 1.30Kgf min. per pin
8.3	Latch Retention force	Samples should be exposed 72h Min. at ambient atmosphere after molding. Apply axial pull out force at the speed rate of 25± 3 mm/min.	Initial: 2.55Kgf min. After 50 cycles(Press force is 0.51Kgf max.):2.35Kgf min.

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.52 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Solder ability	Lead-Free Process: Soldering time: 5 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CID6 Series Connector System	SPEC.NO.: SPCI125A
REVISIONS			PAGE: 3/3

	ITEM	TEST CONDITION	REQUIREMENT
9.4	Resistance to soldering heat	DIP Type Lead-Free Process Soldering time: 5 ± 0.5 second Soldering pot: $260 \pm 5^{\circ}\text{C}$	No damage
9.5	High Temperature	A mated connector shall be placed in a heat oven of the following conditions. After the test, contact resistance shall be measured. Temperature: $125 \pm 2^{\circ}\text{C}$ Duration: 44 hours	Appearance: No damage
9.6	Low Temperature	Chamber temperature: $-40 \pm 3^{\circ}\text{C}$, Duration: 44 hours.	Appearance: No damage
9.7	Humidity	$40 \pm 2^{\circ}\text{C}$, 90-95% RH , 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage
9.8	Temperature cycling	One cycle consists of : (1)- 55^{+0}_{-3} °C , 30 min. (2)Room temp. 10-15 min. (3) 125^{+3}_{-0} °C , 30 min. (4)Room temp. 10-15 min. (Teat cycle: 5 cycles)	Appearance: No damage
9.9	Salt spray	Temperature: $35 \pm 2^{\circ}\text{C}$ Salt solution concentration: 5 % in weight Duration: 8 hours Measurement must be taken after water rinse	Appearance: No damage
9.10	Hydrogen Sulfide (H2S) Exposure	Temperature: $40 \pm 2^{\circ}\text{C}$ Relative humidity: 75~80 % H2S Density: 10 ± 5 ppm Duration: 96 hours	Appearance: No damage Contact resistance: 30 mΩ max.

10. Service temperature: -55 to $+105^{\circ}\text{C}$
Storage temperature: -25 to $+85^{\circ}\text{C}$